

**SILICON GATE CMOS****65,536 WORD x 16 BIT CMOS STATIC RAM****Description**

The TC551664J is a 1,048,576 bit high speed CMOS static random access memory organized as 65,536 words by 16 bits and operated from a single 5V supply. Toshiba's advanced CMOS technology and circuit design enable high speed operation.

The TC551664J features low power dissipation when the device is deselected using chip enable ( $\overline{CE}$ ), and has an output enable input ( $\overline{OE}$ ) for fast memory access. Byte access is supported by upper and lower byte controls.

The TC551664J is suitable for use in high speed applications such as cache memory and high speed storage. All inputs and outputs are TTL compatible.

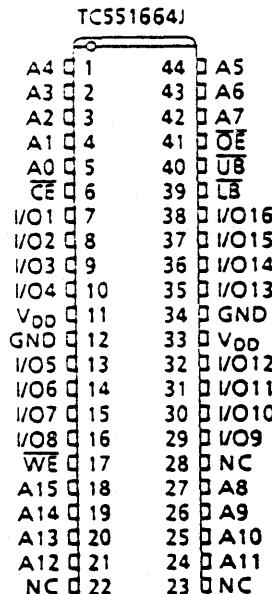
The TC551664J is available in a 400mil width, 44-pin SOJ suitable for high density surface assembly.

**Features**

- Fast access time
  - TC551664J -15 15ns (max.)
  - TC551664J -20 20ns (max.)
  - TC551664J -25 25ns (max.)
- Low power dissipation

Cycle Time	15	20	25	30	50	ns
Operation (max.)	260	220	200	180	150	mA

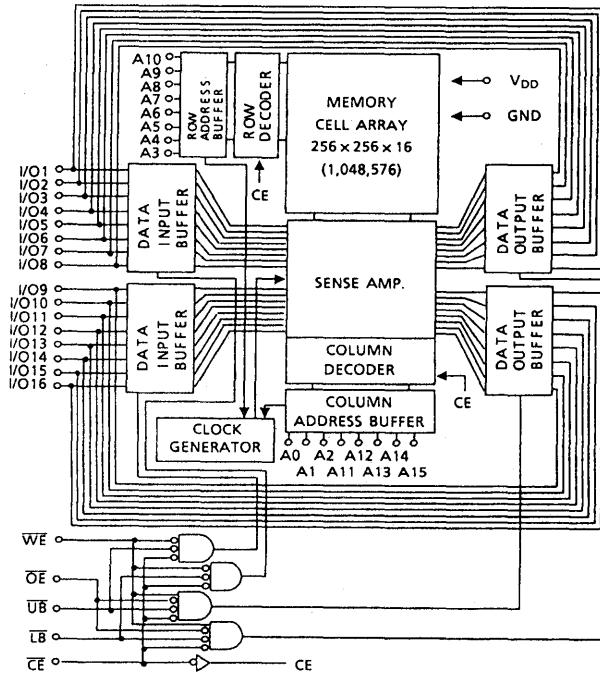
- Standby: 1mA (max.)
- Single 5V power supply: 5V $\pm$ 10%
- Fully static operation
- Inputs and outputs TTL compatible
- Output buffer control:  $\overline{OE}$
- Data byte controls: LB, UB
- Package: SOJ44-P-400

**Pin Connection (Top View)**

(SOJ)

**Pin Names**

A0 ~ A15	Address Inputs
I/O1 ~ I/O16	Data Inputs/Outputs
CE	Chip Enable Input
WE	Write Enable Input
$\overline{OE}$	Output Enable Input
LB, UB	Data Byte Control Inputs
V <sub>DD</sub>	Power (+5V)
GND	Ground
NC	No Connection

**Block Diagram****Operating Mode**

MODE	PIN	$\overline{CE}$	$\overline{OE}$	$\overline{WE}$	$\overline{LB}$	$\overline{UB}$	I/01 ~ I/08	I/09 ~ I/16	POWER
Read		L	L	H	L	L	Output	Output	$I_{DDO}$
					H	L	High Impedance	Output	$I_{DDO}$
					L	H	Output	High Impedance	$I_{DDO}$
Write		L	*	L	L	L	Input	Input	$I_{DDO}$
					H	L	High Impedance	Input	$I_{DDO}$
					L	H	Input	High Impedance	$I_{DDO}$
Output Disable	L	H	H	*	*	*	High Impedance	High Impedance	$I_{DDO}$
	L	*	*	H	H	*	High Impedance	High Impedance	$I_{DDO}$
Standby	H	*	*	*	*	*	High Impedance	High Impedance	$I_{DDS}$

\*H or L

**Maximum Ratings**

SYMBOL	ITEM	RATING	UNIT
$V_{DD}$	Power Supply Voltage	-0.5 ~ 7.0	V
$V_{IN}$	Input Voltage	-2.0* ~ 7.0	V
$V_{I/O}$	Input/Output Voltage	-0.5* ~ $V_{DD} + 0.5$	V
$P_D$	Power Dissipation	1.5	W
$T_{SOLDER}$	Soldering Temperature • Time	260 • 10	°C • sec
$T_{STRG}$	Storage Temperature	-65 ~ 150	°C
$T_{OPR}$	Operating Temperature	-10 ~ 85	°C

\*-3V with a pulse width of 10ns

**DC Recommended Operating Conditions**

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT
$V_{DD}$	Power Supply Voltage	4.5	5.0	5.5	V
$V_{IH}$	Input High Voltage	2.2	—	$V_{DD} + 0.5$	V
$V_{IL}$	Input Low Voltage	-0.5*	—	0.8	V

\* -3V with a pulse width of 10ns

**DC Characteristics (Ta = 0 ~ 70°C,  $V_{DD} = 5V \pm 10\%$ )**

SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
$I_{LI}$	Input Leakage Current	$V_{IN} = 0 \sim V_{DD}$	—	—	$\pm 10$	$\mu A$
$I_{LO}$	Output Leakage Current	$\overline{CE} = V_{IH}$ or $\overline{WE} = V_{IL}$ or $\overline{OE} = V_{IH}$ $V_{OUT} = 0 \sim V_{DD}$	—	—	$\pm 10$	$\mu A$
$I_{OH}$	Output High Current	$V_{OH} = 2.4V$	-4	—	—	$mA$
$I_{OL}$	Output Low Current	$V_{OL} = 0.4V$	8	—	—	$mA$
$I_{DDO}$	Operating Current	$\overline{CE} = V_{IL}$ , $I_{OUT} = 0mA$ , Other Inputs = $V_{IH}/V_{IL}$	$t_{cycle} = 15ns$	—	260	$mA$
			$t_{cycle} = 20ns$	—	220	
			$t_{cycle} = 25ns$	—	200	
			$t_{cycle} = 30ns$	—	180	
			$t_{cycle} = 50ns$	—	150	
$I_{DDS1}$	Standby Current	$CE = V_{IH}$ , Other Inputs = $V_{IH}/V_{IL}$	—	—	30	$mA$
$I_{DDS2}$			—	—	1	

**Capacitance\* (Ta = 25°C, f = 1.0MHz)**

SYMBOL	PARAMETER	TEST CONDITION	MAX.	UNIT
$C_{IN}$	Input Capacitance	$V_{IN} = GND$	6	$pF$
$C_{I/O}$	Input/Output Capacitance	$V_{I/O} = GND$	8	$pF$

\*This parameter is periodically sampled and is not 100% tested.

**AC Characteristics (Ta = 0 ~ 70°C<sup>(1)</sup>, V<sub>DD</sub> = 5V±10%)****Read Cycle**

SYMBOL	PARAMETER	TC551664J -15		TC551664J -20		TC551664J -25		UNIT ns
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
t <sub>RC</sub>	Read Cycle Time	15	—	20	—	25	—	
t <sub>ACC</sub>	Address Access Time	—	15	—	20	—	25	
t <sub>CO</sub>	CE Access Time	—	15	—	20	—	25	
t <sub>OE</sub>	OE Access Time	—	8	—	10	—	12	
t <sub>BA</sub>	UB, LB Access Time	—	8	—	10	—	12	
t <sub>OH</sub>	Output Data Hold Time from Address Change	5	—	5	—	5	—	
t <sub>COE</sub>	Output Enable Time from CE	5	—	5	—	5	—	
t <sub>OEE</sub>	Output Enable Time from OE	1	—	1	—	1	—	
t <sub>BE</sub>	Output Enable Time from UB, LB	1	—	1	—	1	—	
t <sub>COD</sub>	Output Disable Time from CE	—	8	—	8	—	8	
t <sub>ODO</sub>	Output Disable Time from OE	—	8	—	8	—	8	
t <sub>BD</sub>	Output Disable Time from UB, LB	—	8	—	8	—	8	

**Write Cycle**

SYMBOL	PARAMETER	TC551664J -15		TC551664J -20		TC551664J -25		UNIT ns
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
t <sub>WC</sub>	Write Cycle Time	15	—	20	—	25	—	
t <sub>WP</sub>	Write Pulse Width	9	—	10	—	12	—	
t <sub>CW</sub>	Chip Enable to End of Write	12	—	13	—	15	—	
t <sub>BW</sub>	UB, LB Enable to End of Write	9	—	12	—	14	—	
t <sub>AW</sub>	Address Valid to End of Write	9	—	12	—	14	—	
t <sub>AS</sub>	Address Setup Time	0	—	0	—	0	—	
t <sub>WR</sub>	Write Recovery Time	0	—	0	—	0	—	
t <sub>DS</sub>	Data Setup Time	8	—	10	—	10	—	
t <sub>DH</sub>	Data Hold Time	0	—	0	—	0	—	
t <sub>OEW</sub>	Output Enable Time from WE	1	—	1	—	1	—	
t <sub>ODW</sub>	Output Disable Time from WE	—	8	—	8	—	8	

**AC Test Conditions**

Input Pulse Levels	3.0V/0.0V
Input Pulse Rise and Fall Time	3ns
Input Timing Measurement Reference Levels	1.5V
Output Timing Measurement Reference Levels	1.5V
Output Load	Fig. 1

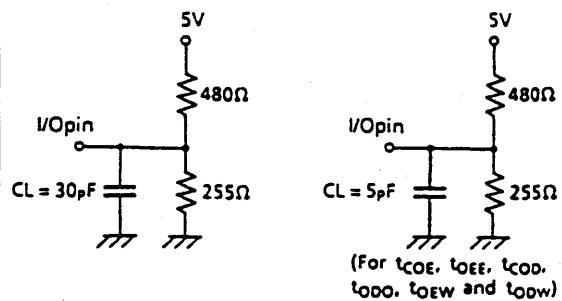
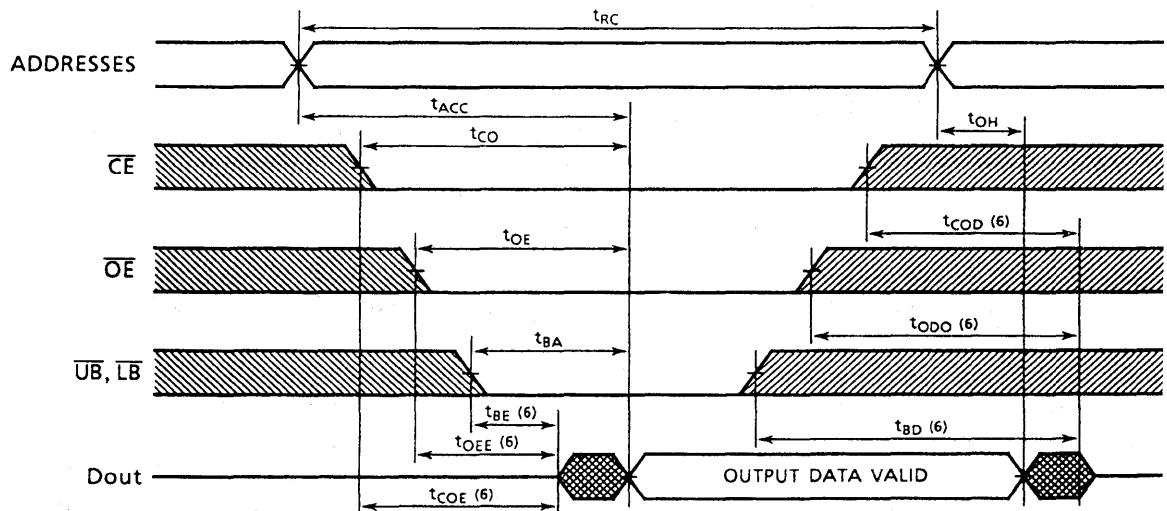


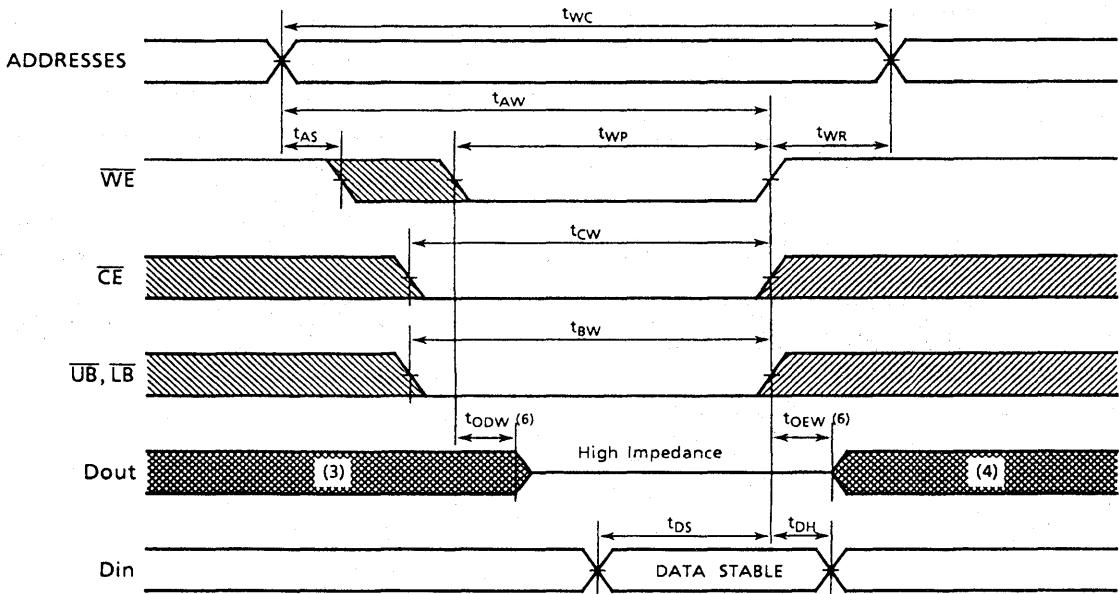
Figure 1.

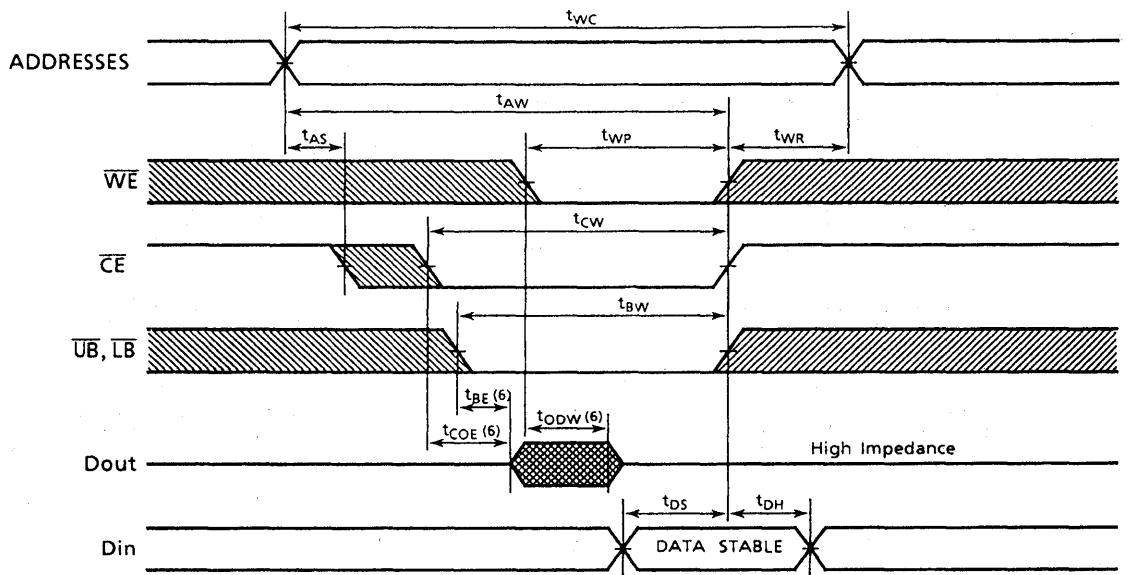
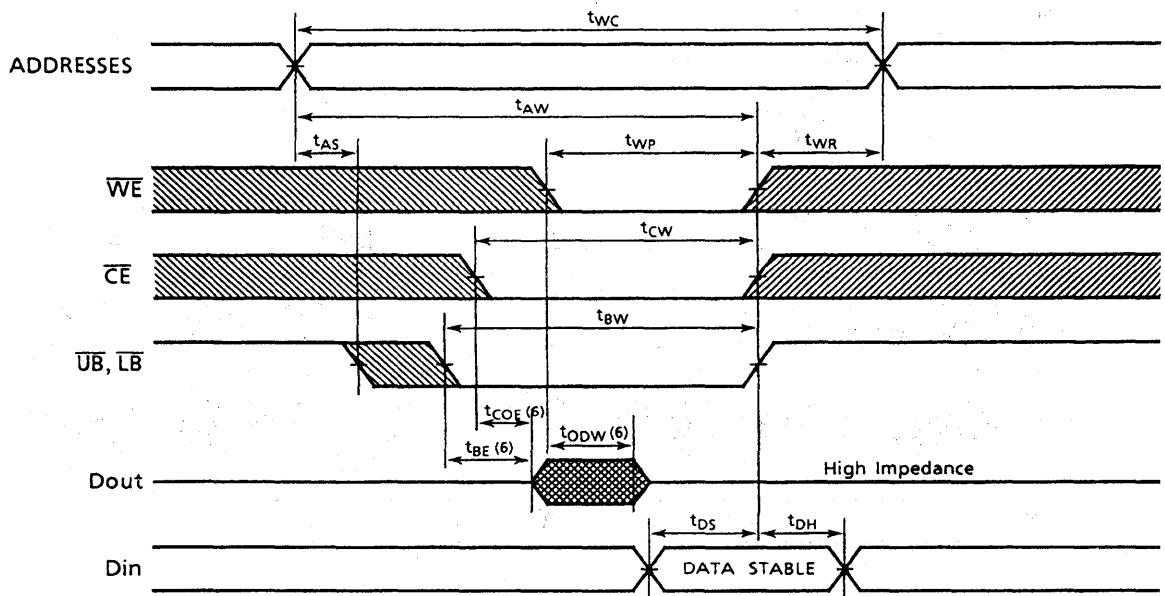
## Timing Waveforms

### Read Cycle (2)



### Write Cycle 1 (5) ( $\overline{WE}$ Controlled)



Write Cycle 2<sup>(5)</sup> (CE Controlled)Write Cycle 3<sup>(5)</sup> (UB, LB Controlled)

## Notes:

1. The operating temperature ( $T_a$ ) is guaranteed with transverse air flow exceeding 400 linear feet per minute.
2.  $\overline{WE}$  is high for read cycles.
3. If the  $\overline{CE}$  low transition occurs coincident with or after the  $\overline{WE}$  low transition, outputs remain in a high impedance state.
4. If the  $\overline{CE}$  high transition occurs coincident with or prior to the  $\overline{WE}$  high transition, outputs remain in a high impedance state.
5. If  $\overline{OE}$  is high during a write cycle, the outputs are in a high impedance state during this period.
6. The following parameters are measured using the load shown in Fig. 1.
  - (A)  $t_{COE}, t_{OEE}, t_{BE}, t_{OEW} \dots$  Output Enable Time
  - (B)  $t_{COD}, t_{ODO}, t_{BD}, t_{ODW} \dots$  Output Disable Time

